## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yin et al.

Serial No.: 09/293,188

Filed: April 16, 1999

For: METHOD OF FORMING

INTERCONNECT STRUCTURE WITH INTERLAYER DIELECTRIC (as amended)

Confirmation No.: 4546

Examiner: P. Cao

Group Art Unit: 2814

Attorney Docket No.: 2269-6910.1US

(97-1121.01/US)

Notice of Allowance Mailed:

May 24, 2007

VIA ELECTRONIC FILING

**AUGUST 10, 2007** 

## AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 3 of this paper;

Amendments to the Abstract appear on page 6 of this paper;

Amendments to the claims are set forth in the listing of the claims that begins on page 7 of this paper; and

Remarks start at page 12 of this paper.